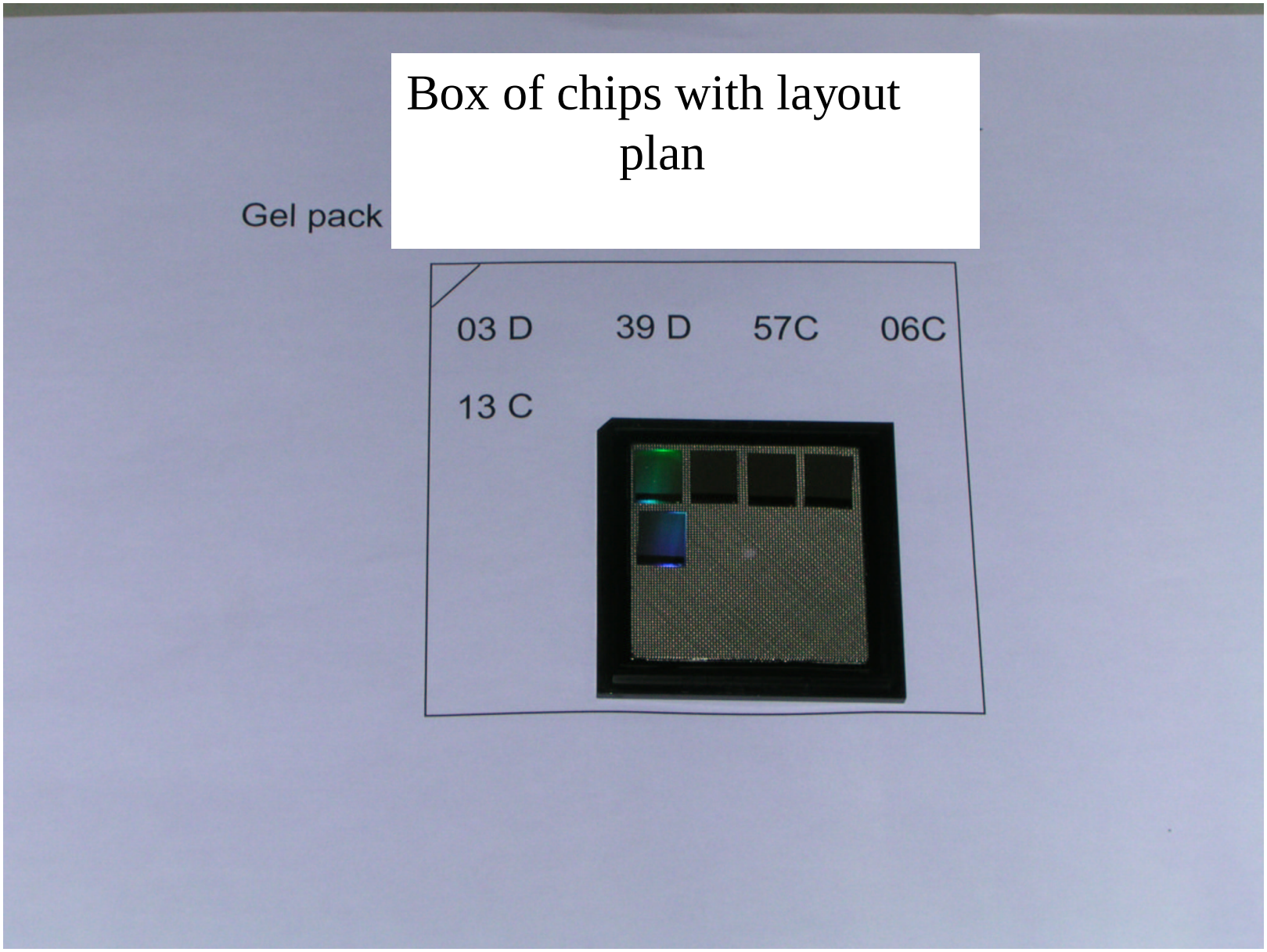
Box of chips with layout plan



Fraunhofer Institut Zuverlässigkeit und Mikrointegration

Covering Letter

Institutsleitung
Prof. Dr.-Ing. Dr. E. h. Herbert Reichl

Mr. Bruno Gobbi
Fermi National Accelerator Laboratory
Kirk and Wilson Streets
Receiving Department
Batavia, IL 60510
Att: Bruno Gobbi, Lab C
Tel: 630 840 3860

FhG-IZM Berlin
Sekr. TIB 4/2-1
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13355 Berlin

von
Katrin Scherpinski
Tel. +49-30-46403-601
Fax. +49-30-314-72835
email
Katrin.Scherpinski@izm.fraunhofer.de

Berlin 08.07.2005

Dear Bruno,

with this you will receive 1 gel pack with 5 bumped chips from wafer K7MWH6T. This chips are class AA. Some of them have some small defects after bumping.
Chip 03 D Platig defect ➔ missing bumps and shorts
Chip 39 D
Chip 57 C 2 missing bumps
Chip 06 C particles/ residues
Chip 13 C

Attached you will find the mapping plan with the chip numbers on the wafer map and a plan of the gel pack.

If there are any questions, please do not hesitate to contact me.

Best regards

Katrin Scherpinski, Fraunhofer IZM
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Fax.: 0049 30 46403-601
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Berlin,
July 8, 2005

Pro Forma Invoice

This parcel contains

5 Silicon devices for detection of subatomic particles.

They have no commercial value. For researce only.

(US Custom broker in Chicago: c/o E. Besler 1-847-364-0300)

Custom value: 100 USD

FRAUNHOFER INSTITUT ZUVERLÄSSIGKEIT UND MIKROINTEGRATION
Gustav-Meyer-Allee 25
13355 Berlin

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Fraunhofer-Gesellschaft zur Förderung der angewandten Forschung e.V., München
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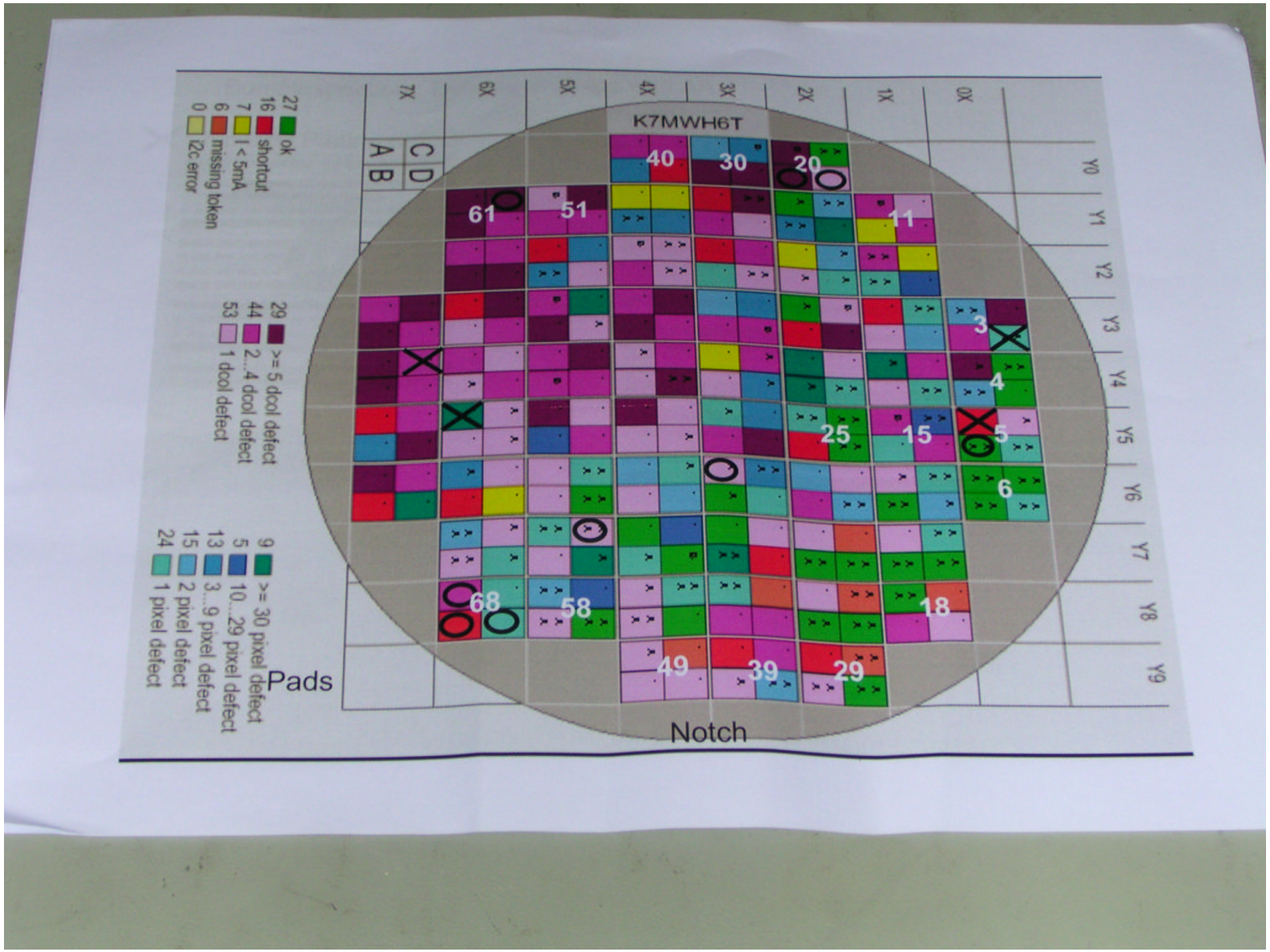
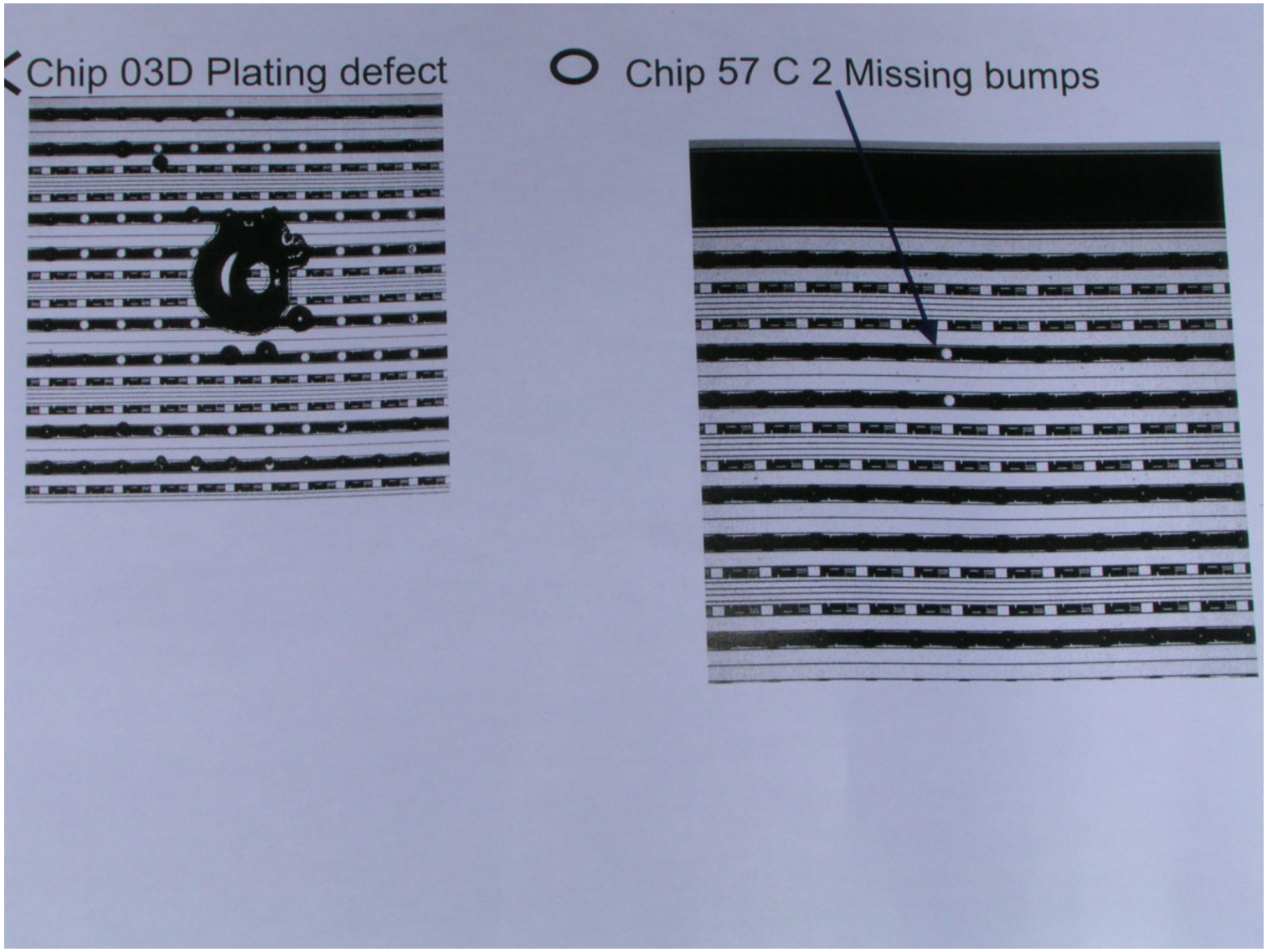

K7MWH6T
Y0
Y1
Y2
Y3
Y4
Y5
Y6
Y7
Y8
Y9
0X
1X
2X
3X
4X
5X
6X
7X
A
B
C
D
Pads
Notch
27 ok
16 shortcut
7 I < 5mA
6 missing token
0 i2c error
29 >= 5 dcol defect
44 2...4 dcol defect
53 1 dcol defect
9 >= 30 pixel defect
5 10...29 pixel defect
13 3...9 pixel defect
15 2 pixel defect
24 1 pixel defect


Chip 03D Plating defect
Chip 57 C 2 Missing bumps